


DATA BOOK PACKAGE OUTLINE

PREVIEW

LEADFRAME EXAMPLE
4212695

DRAFTER: ANIS FAUZI	DATE: 11/20/2017		DIMENSIONS IN MILLIMETERS			
DESIGNER:	DATE:	 TEXAS INSTRUMENTS <small>SEMICONDUCTOR OPERATIONS</small>				
CHECKER: K. SINCERBOX	DATE: 11/20/2017					
ENGINEER: AARON HENG	DATE: 11/20/2017	ePOD, NEB0003A / TO-220, 3 PIN, 2.54 MM PITCH				
APPROVED: EUGENE LEE & DAVID CHIN	DATE: 11/20/2017					
RELEASED: WDM	DATE: 11/20/2017					
TEMPLATE INFO: EDGE# 4218519	DATE: 03/20/2013	SCALE 3X	SIZE A	4215013	REV A	PAGE 1 OF 4

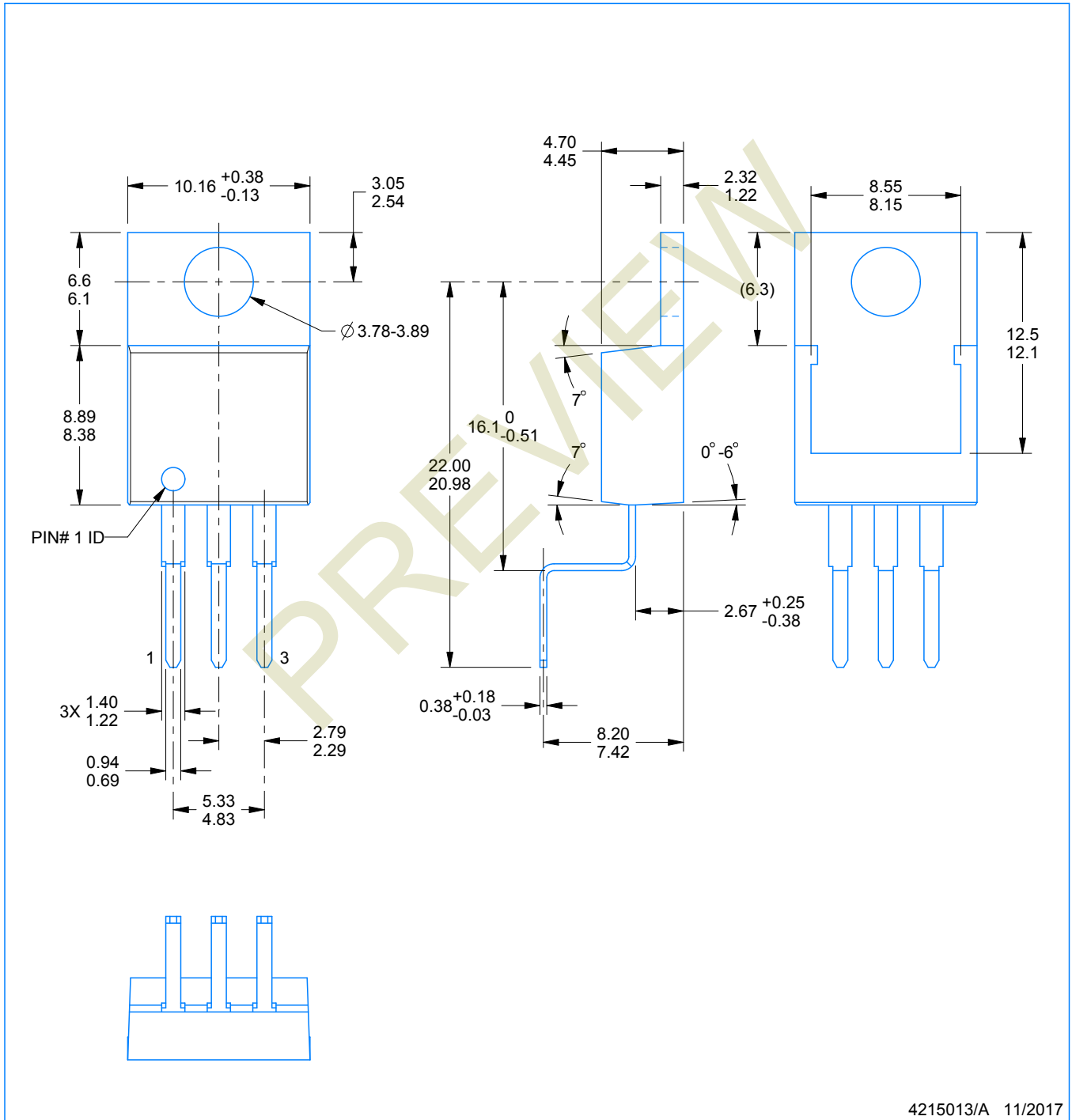
NEB0003A



PACKAGE OUTLINE

TO-220 - 19.65 mm max height

TO-220



4215013/A 11/2017

NOTES:

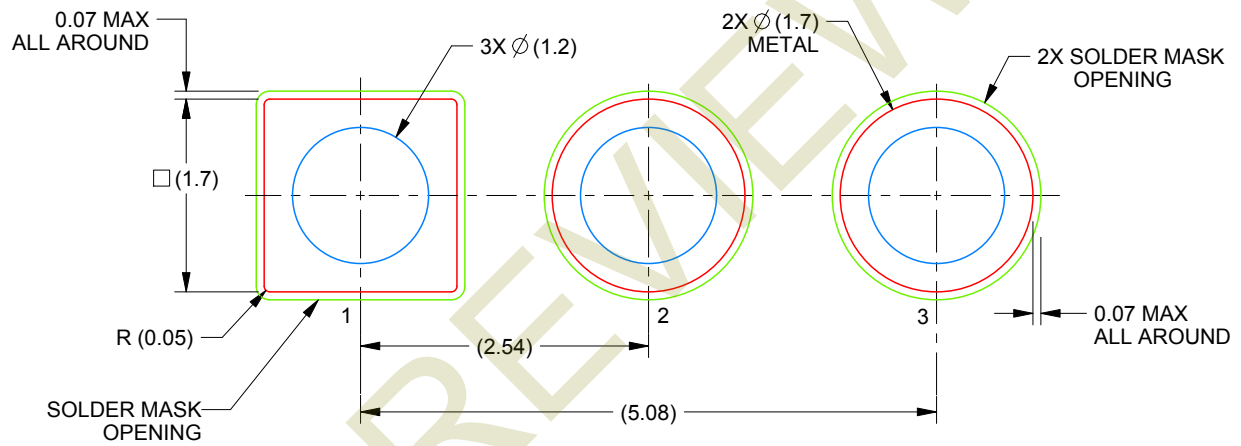
1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Reference JEDEC registration TO-220.

EXAMPLE BOARD LAYOUT

NEB0003A

TO-220 - 19.65 mm max height

TO-220



LAND PATTERN EXAMPLE
NON-SOLDER MASK DEFINED
SCALE: 15X

4215013/A 11/2017

REVISIONS

REV	DESCRIPTION	ECR	DATE	ENGINEER / DRAFTSMAN
A	RELEASE NEW DRAWING	2168417	11/20/2017	AARON HENG / ANIS FAUZI

PREVIEW